1. DESCRIPTION

The XLA1044 is part of the family of high-speed CAN transceivers. It provides an interface between a Controller Area Network (CAN) protocol controller and the physical two-wire CAN bus. The transceiver is designed for high-speed CAN applications in the automotive industry, providing the differential transmit and receive capability to (a microcontroller with) a CAN protocol controller.

The XLA1044 offers a feature set optimized for 12 V automotive applications, Significant improvements have been made, and excellent ElectroMagnetic Compatibility (EMC) performance. Additionally, the XLA1044 features:

● Ideal passive behavior to the CAN bus when the supply voltage is off

● A very low-current Standby mode with bus wake-up capability

● Excellent EMC performance, even without a common mode choke

● Variants with a VIO pin can be interfaced directly with microcontrollers with supply voltages from 3.3 V to 5 V

These features make the XLA1044 an excellent choice for all types of HS-CAN, in nodes that require a low-power mode with wake-up capability via the CAN bus.

The XLA1044 implements the CAN physical layer as defined in ISO 11898-2:2016 and SAE J2284-1 to SAE J2284-5. The XLA1044T is specified for data rates up to 1 Mbit/s. Additional timing parameters defining loop delay symmetry are specified for the other variants. This implementation enables reliable communication in the CAN FD fast phase at data rates up to 5 Mbit/s.

2. FEATURES

2.1. General

● Fully ISO 11898-2:2016, SAE J2284-1 to SAE J2284-5 and SAE J1939-14 compliant

● Very low-current Standby mode with local and bus wake-up capability

● Optimized for use in 12 V automotive systems

● Low Electromagnetic Emission (EME) and high Electromagnetic Immunity (EMI),

● according to proposed EMC Standards IEC 62228-3 and SAE J2962-2

● Dark green product (halogen free and Restriction of Hazardous Substances (RoHS) compliant)

● Variants with a VIO pin allow for direct interfacing with 3.3 V to 5 V microcontrollers. Variants without a VIO pin can interface with 3.3V and 5 V-supplied microcontrollers, provided the microcontroller I/Os are 5 V tolerant.

2.2. Predictable and fail-safe behavior

- Functional behavior predictable under all supply conditions

- Transceiver disengages from the bus (high-ohmic) when the supply voltage drops below the switch-off undervoltage threshold

- Transmit Data (TXD) dominant time-out functions

- Internal biasing of TXD and STB input pins

2.3. Low-power management

- Very low-current Standby mode with host and bus wake-up capability

- Variants with V_{IO} pin: CAN wake-up receiver powered by VIO allowing VCC to be shut down

2.4. Protection

- High ESD handling capability on the bus pins (8 kV IEC and HBM)

- Bus pins protected against transients in automotive environments

- Undervoltage detection on pins V_{CC} and V_{IO}

- Thermally protected

3. QUICK REFERENCE DATA

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		4.5	-	5.5	V
I_{CC}	supply current	Standby mode				
		XLA1044T,GT	-	10	15	µA
		variants with a V_{IO} pin	-	0.1	1	µA
		Normal mode				
		bus recessive	2	5	10	
		bus dominant	20	45	60	mA
$V_{uvd(stb)(VCC)}$	standbyundervoltage detection voltage on pin V_{CC}		3.5	4	4.3	mA
$V_{uvd(swoff)(VCC)}$	switch-off undervoltage detection voltage on pin V_{CC}	XLA1044T,GT	1.3	2.4	3.4	V
V_{IO}	supply voltage on pin V_{IO}		2.91	-	5.5	V
I_{IO}	supply current on pin V_{IO}	Standby mode	-	10	16.5	µA
		Normal mode; bus recessive	10	17	30	µA
		variants with a V_{IO} pin	-	170	300	µA
$V_{uvd(swoff)(VIO)}$	switch-off undervoltage detection voltage on pin V_{IO}	variants with a V_{IO} pin	2.4	2.6	2.8	V
V_{ESD}	electrostatic discharge voltage	IEC 61000-4-2 at pins CANH and CANL	-8	-	+8	kV
V_{CANH}	voltage on pin CANH	limiting value according to IEC60134	-42	-	+42	V
V_{CANL}	voltage on pin CANL	limiting value according to IEC60134	-42	-	+42	V
T_{vj}	virtual junction temperature		-40	-	+150	°C

4. BLOCK DIAGRAM

1. Pin 5 is not connected in non-VIO product variants.
2. V_{IO} = V_{CC} in non-V_{IO} product variants.
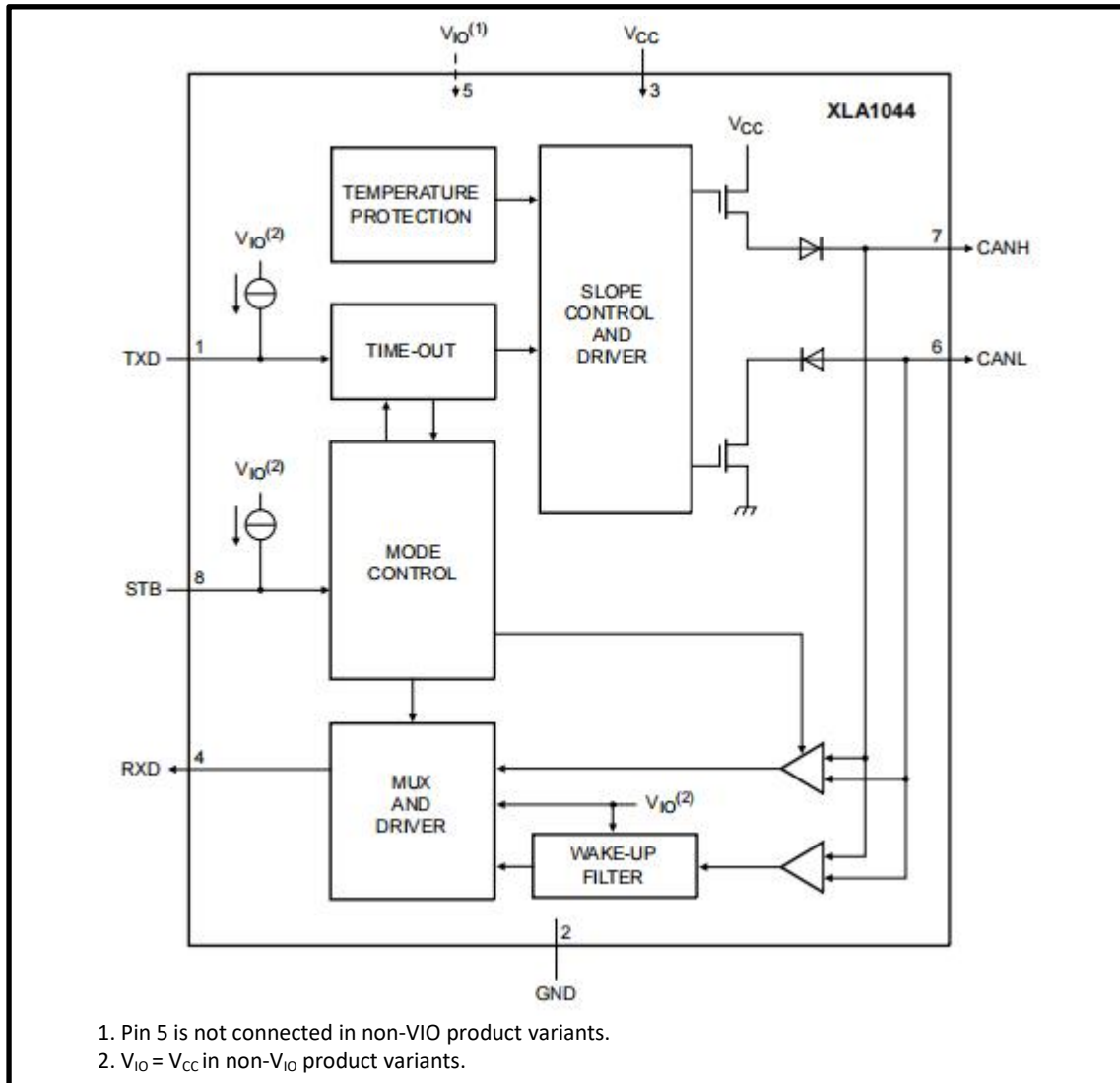
Figure 1. Block diagram

5.   PINNING INFORMATION

5.1.   Pinning

XLA1044T
XLA1044GT

TXD 1 | 8 STB
GND 2 | 7 CANH
V$_{CC}$ 3 | 6 CANL
RXD 4 | 5 n.c.
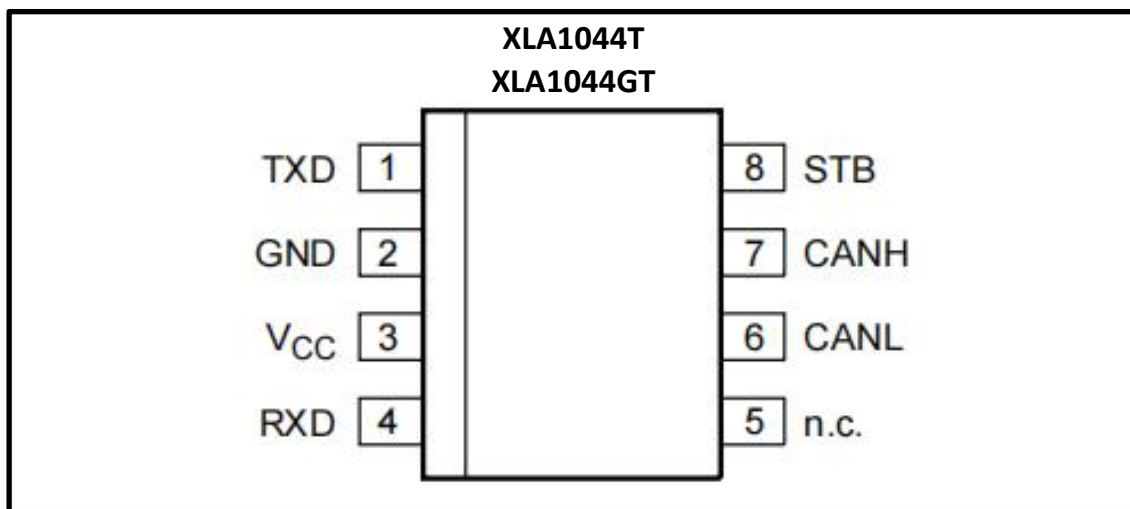
Figure 2. Pin configuration diagrams

5.2.   Pin description

Table 3. Pin description

Symbol	Pin	Type[1]	Description
TXD	1	I	transmit data input
GND	2	G	ground supply
V$_{CC}$	3	P	supply voltage
RXD	4	O	receive data output; reads out data from the bus lines
n.c.	5	`	ot connected; XLA1044T,GT
CANL	6	AIO	LOW-level CAN bus line
CANH	7	AIO	HIGH-level CAN bus line
STB	8	I	Standby mode control input

[1] I: digital input; O: digital output; AIO: analog input/output; P: power supply; G: ground.

6. FUNCTIONAL DESCRIPTION

6.1. Operating modes

The XLA1044 supports two operating modes, Normal and Standby. The operating mode is selected via pin STB. See Table 4 for a description of the operating modes under normal supply conditions.

Table 4. Operating modes

Mode	Inputs		Outputs	
	Pin STB	Pin TXD	CAN driver	Pin RXD
Normal	LOW	LOW	dominant	LOW
		HIGH	recessive	LOW when bus dominant
				HIGH when bus recessive
Standby	HIGH	x [1]	biased to ground	follows BUS when wake-up detected
				HIGH when no wake-up detected

Note:[1] 'x' = don't care

6.1.1 Normal mode

A LOW level on pin STB selects Normal mode. In this mode, the transceiver can transmit and receive data via the bus lines CANH and CANL (see Figure 1 for the block diagram). The differential receiver converts the analog data on the bus lines into digital data which is output on pin RXD. The slopes of the output signals on the bus lines are controlled internally and are optimized in a way that guarantees the lowest possible EME.

6.1.2 Standby mode

A HIGH level on pin STB selects Standby mode. In Standby mode, the transceiver is not able to transmit or correctly receive data via the bus lines. The transmitter and Normalmode receiver blocks are switched off to reduce supply current, and only a low-power differential receiver monitors the bus lines for activity.

In Standby mode, the bus lines are biased to ground to minimize system supply current. The low-power receiver is supplied from V_{IO} (V_{CC} in non-V_{IO} variants) and can detect CAN bus activity even if V_{IO} is the only available supply voltage. Pin RXD follows the bus after a wake-up request has been detected. A transition to Normal mode is triggered when STB is forced LOW.

6.2. Remote wake-up (via the CAN bus)

The XLA1044 wakes up from Standby mode when a dedicated wake-up pattern (specified in ISO 11898-2:2016) is detected on the bus. This filtering helps avoid spurious wake-up events. A spurious wake-up sequence could be triggered by, for example, a dominant clamped bus or by dominant phases due to noise or spikes on the bus. The wake-up pattern consists of:

● a dominant phase of at least $t_{wake(busdom)}$ followed by
● a recessive phase of at least $t_{wake(busrec)}$ followed by
● a dominant phase of at least $t_{wake(busdom)}$

Dominant or recessive bits between the above mentioned phases that are shorter than $t_{wake(busdom)}$ and $t_{wake(busrec)}$ respectively are ignored.

The complete dominant-recessive-dominant pattern must be received within $t_{to(wake)bus}$ to be recognized as a valid wake-up pattern (see Figure 3). Otherwise, the internal wake-up logic is reset. The complete wake-up pattern will then need to be retransmitted to trigger a wake-up event. Pin RXD remains HIGH until the wake-up event has been triggered.

After a wake-up sequence has been detected, the XLA1044 will remain in Standby mode with the bus signals reflected on RXD. Note that dominant or recessive phases lasting less than tfltr(wake)bus will not be detected by the low-power differential receiver and will not be reflected on RXD in Standby mode. A wake-up event is not flagged on RXD if any of the following events occurs while a valid wake-up pattern is being received:

The XLA1044 switches to Normal mode

The complete wake-up pattern was not received within tto(wake)bus

A V_{CC} or V_{IO} undervoltage is detected ($V_{CC} < V_{uvd(swoff)}(V_{CC})$ or $V_{IO} < V_{uvd(swoff)}(V_{IO})$; see Section 6.3.3)
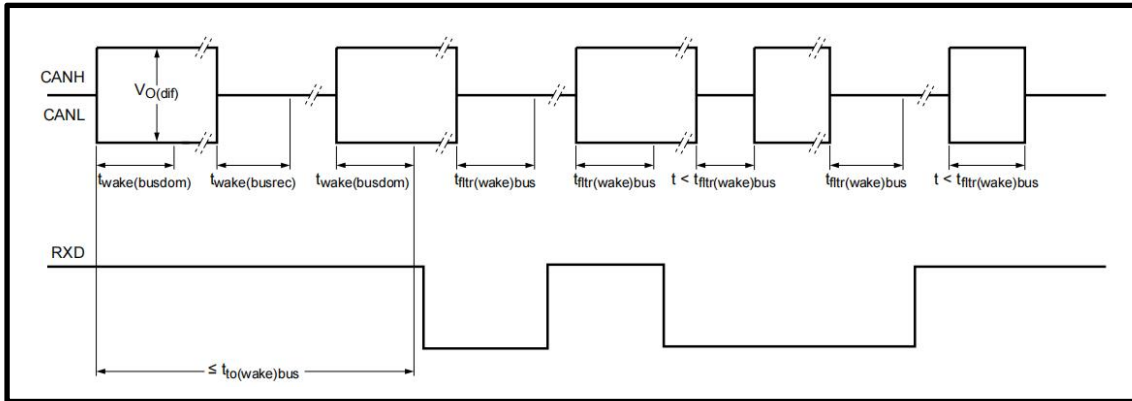

Figure 3. Wake-up timing

6.3. Fail-safe features

6.3.1 TXD dominant time-out function

A 'TXD dominant time-out' timer is started when pin TXD is set LOW. If the LOW state on this pin persists for longer than $t_{to(dom)TXD}$, the transmitter is disabled, releasing the bus lines to recessive state. This function prevents a hardware and/or software application failure from driving the bus lines to a permanent dominant state (blocking all network communications). The TXD dominant time-out timer is reset when pin TXD is set HIGH.

6.3.2 Internal biasing of TXD and STB input pins

Pins TXD and STB have internal pull-ups to V_{CC} (V_{IO} for variants with a V_{IO} pin) to ensure a safe, defined state in case one or both of these pins are left floating. Pull-upcurrents flow in these pins in all states; both pins should be held HIGH in Standby mode to minimize supply current.

6.3.3 Undervoltage detection on pins VCC and VIO

If V_{CC} drops below the standby undervoltage detection level, $V_{uvd(stb)}(V_{CC})$, the transceiver switches to Standby mode. The logic state of pin STB is ignored until VCC has recovered.

In versions with a V_{IO} pin, if V_{IO} drops below the switch-off undervoltage detection level ($V_{uvd(swoff)}(V_{IO})$), the transceiver switches off and disengages from the bus (zero load) until V_{IO} has recovered.

In versions without a V_{IO} pin, if V_{CC} drops below the switch-off undervoltage detection level ($V_{uvd(swoff)}(V_{CC})$), the transceiver switches off and disengages from the bus (zero load) until V_{CC} has recovered.

6.3.4   Overtemperature protection

The output drivers are protected against overtemperature conditions. If the virtual junction temperature exceeds the shutdown junction temperature, $T_j(sd)$, both output drivers are disabled. When the virtual junction temperature drops below $T_j(sd)$ again, the output drivers recover once TXD has been reset to HIGH. Including the TXD condition prevents output driver oscillation due to small variations in temperature.

7. LIMITING VALUES

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134); all voltages are referenced to ground.

Symbol	Parameter	Conditions	Min	Max	Unit
V_X	voltage on pin x[1]	on pins CANH, CANL	-45	+42	V
		on pin VCC, VIO	-0.3	+7	V
		on any other pin [2]	-0.3		V
$V_{(CANH-CANL)}$	voltage between pin CANH and pin CANL		27	+27	V
V_{trt}	transient voltage	on pins CANH and CANL [4]		V_{IO} + 0.3[3]	
		pulse 1	-100	-	V
		pulse 2a	-	75	V
		pulse 3a	-150	-	V
		pulse 3b	-	100	V
V_{ESD}	electrostatic discharge voltage	IEC 61000-4-2 (150 pF, 330 Ω discharge circuit) [5]			
		on pins CANH and CANL	-8	+8	kV
		Human Body Model (HBM)			
		on any pin [6]	-4	+4	kV
		on pins CANH and CANL [7]	-8	+8	kV
		Machine Model (MM); 200 pF, 0.75 µH, 10 Ω [8]			
		on any pin	-200	+200	V
		Charged Device Model (CDM) [9]			
		on corner pins	-750	+750	V
		on any other pin	-500	+500	V
T_{vj}	virtual junction temperature	[10]	-40	+125	°C
T_{stg}	storage temperature	[11]	-55	+150	°C

Note:

(1) The device can sustain voltages up to the specified values over the product lifetime, provided applied voltages (including transients) never exceed these values.

(2) Maximum voltage should never exceed 7 V.

(3) V_{CC} + 0.3 in the non-V_{IO} product variants.

(4) Verified by an external test house according to IEC TS 62228, Section 4.2.4; parameters for standard pulses defined in ISO 7637.

(5) Verified by an external test house according to IEC TS 62228, Section 4.3.

(6) In accordance with IEC 60747-1. An alternative definition of virtual junction temperature is: $T_{vj} = T_{amb} + P \times R_{th(vj-a)}$, where $R_{th(vj-a)}$ is a fixed value to be used for the calculation of T_{vj}. The rating for T_{vj} limits the allowable combinations of power dissipation (P) and ambient temperature (T_{amb}).

(7) T_{stg} in application according to IEC61360-4. For component transport and storage conditions, see instead IEC61760-2

8. THERMAL CHARACTERISTICS

Table 6. Thermal characteristics

Value determined for free convection conditions on a JEDEC 2S2P board.

Symbol	Parameter	Conditions[(1)]	Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	SOP8 package; in free air	94	K/W
Ψ_{j-top}	thermal characterization parameter from junction to top of package	SOP8 package; in free air	13	K/W

Note:(1) According to JEDEC JESD51-2, JESD51-5 and JESD51-7 at natural convection on 2s2p board. Board with two inner copper layers (thickness: 35 μm) and thermal via array under the exposed pad connected to the first inner copper layer (thickness: 70 μm)

9. STATIC CHARACTERISTICS

Table 7. Static characteristics

Tvj = -40 °C to +125°C; V$_{CC}$ = 4.5 V to 5.5 V; V$_{IO}$ = 2.91 V to 5.5 V[1]; R$_{L}$ = 60 Ω; C$_{L}$ = 100 pF unless otherwise specified; all voltages are defined with respect to ground; positive currents flow into the IC.[2]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supply; pin V$_{CC}$						
V$_{CC}$	supply voltage		4.5	-	5.5	V
V$_{uvd(stb)(VCC)}$	standby undervoltage detection voltage on pin V$_{CC}$	[3]	3.5	4	4.3	V
V$_{uvd(swoff)(VCC)}$	switch-off undervoltage detection voltage on pin V$_{CC}$	XLA1044T,GT [3]	1.3	2.4	3.4	V
I$_{CC}$	supply current	Standby mode				
		XLA1044T, GT; V$_{TXD}$ = V$_{CC}$	-	10	15	μA
		variants with a V$_{IO}$ pin; V$_{TXD}$ = V$_{IO}$	-	0.1	1	μA
		Normal mode				
		recessive; V$_{TXD}$ = V$_{IO}$ [4]	2	5	10	mA
		dominant; V$_{TXD}$ = 0 V	20	45	60	mA
		dominant; V$_{TXD}$ = 0 V; short circuit on bus lines; -3 V < (V$_{CANH}$ = V$_{CANL}$) < +18 V	2	80	110	mA
I/O level adapter supply; pin V$_{IO}$ [1]						
V$_{IO}$	supply voltage on pin V$_{IO}$		2.91	-	5.5	V
I$_{IO}$	supply current on pin V$_{IO}$	Standby mode; V$_{TXD}$ = V$_{IO}$ [4]	-	10	16.5	μA
		Normal mode				
		recessive; V$_{TXD}$ = V$_{IO}$ [4]	10	17	30	μA
		dominant; V$_{TXD}$ = 0 V	-	170	300	μA
V$_{uvd(swoff)(VIO)}$	switch-off undervoltage detection voltage on pin V$_{IO}$	variants with a V$_{IO}$ pin [3]	2.4	2.6	2.8	V
Standby mode control input; pin STB						
V$_{IH}$	HIGH-level input voltage	variants with a V$_{IO}$ pin	0.7V$_{IO}$	-	V$_{IO}$+0.3	V
		XLA1044T,GT	2	-	V$_{CC}$+0.3	V
V$_{IL}$	LOW-level input voltage	variants with a V$_{IO}$ pin	-0.3	-	+0.3V$_{IO}$	V
		XLA1044T,GT	-0.3	-	+0.8	V
I$_{IH}$	HIGH-level input current	V$_{STB}$ = V$_{IO}$ [4]	-1	-	+1	μA
I$_{IL}$	LOW-level input current	V$_{STB}$ = 0 V	-15	-	-1	μA
CAN transmit data input; pin TXD						
V$_{IH}$	HIGH-level input voltage	variants with a V$_{IO}$ pin	0.7V$_{IO}$	-	V$_{IO}$+0.3	V
		XLA1044T, GT	2	-	V$_{CC}$+0.3	V
V$_{IL}$	LOW-level input voltage	variants with a V$_{IO}$ pin	-0.3	-	+0.3V$_{CC}$	V
		XLA1044T, GT	-0.3	-	+0.8	V
I$_{IH}$	HIGH-level input current	V$_{TXD}$ = V$_{IO}$ [4]	-5	-	+5	μA

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{IL}	LOW-level input current	$V_{TXD} = 0$ V; variants with a V_{IO} pin	-270	-150	-60	µA
		$V_{TXD} = 0$ V; variants without a V_{IO} pin	-270	-150	-65	µA
C_i	input capacitance	[5]	-	5	10	pF
CAN receive data output; pin RXD						
I_{OH}	HIGH-level output current	$V_{RXD} = V_{IO}$ [4] - 0.4 V	-9	-3	-1	mA
I_{OL}	LOW-level output current	$V_{RXD} = 0.4$ V; bus dominant	1	-	12	mA
Bus lines; pins CANH and CANL						
$V_{O(dom)}$	dominant output voltage	$V_{TXD} = 0$ V; $t < t_{to(dom)TXD}$				
		pin C_{ANH}; $R_L = 50\ \Omega$ to $65\ \Omega$	2.75	3.5	4.5	V
		pin C_{ANL}; $R_L = 50\ \Omega$ to $65\ \Omega$	0.5	1.5	2.25	V
$V_{dom(TX)sym}$	transmitter dominant voltage symmetry	$V_{dom(TX)sym} = V_{CC} - V_{CANH} - V_{CANL}$	-400	-	+400	mV
V_{TXsym}	transmitter voltage symmetry	$V_{TXsym} = V_{CANH} + V_{CANL}$; [5] $f_{TXD} = 250$ kHz, 1 MHz and 2.5 MHz; [6] $C_{SPLIT} = 4.7$ nF	$0.6V_{CC}$	-	$1.1V_{CC}$	V
$V_{O(dif)}$	differential output voltage	dominant; Normal mode; $V_{TXD} = 0$ V; $t < t_{to(dom)TXD}$				
		$R_L = 50\ \Omega$ to $65\ \Omega$	1.5	-	3	V
		$R_L = 45\ \Omega$ to $70\ \Omega$	1.4	-	3.3	V
		$R_L = 2240\ \Omega$	1.5	-	5	V
		recessive				
		Normal mode: $V_{TXD} = V_{IO}$ [4]; no load	-50	-	+50	mV
		Standby mode; no load	-0.2	-	+0.2	V
$V_{O(rec)}$	recessive output voltage	Normal mode; $V_{TXD} = V_{IO}$ [4]; no load	2	$0.5 V_{CC}$	3	V
		Standby mode; no load	-0.1	-	+0.1	V
$V_{th(RX)dif}$	differential receiver threshold voltage	-12 V $\leq V_{CANL} \leq +12$ V; -12 V $\leq V_{CANH} \leq +12$ V				
		Normal mode	0.5	-	0.9	V
		Standby mode	0.4	-	1.15	V
$V_{rec(RX)}$	receiver recessive voltage	-12 V $\leq_{VCANL} \leq +12$ V; -12 V $\leq_{VCANH} \leq +12$ V				
		Normal mode [5]	-4	-	+0.5	V
		Standby mode [5]	-4	-	+0.4	V
$V_{dom(RX)}$	receiver dominant voltage	-12 V $\leq_{VCANL} \leq +12$ V; -12 V $\leq_{VCANH} \leq +12$ V				
		Normal mode [5]	0.9	-	-9.0	V
		Standby mode [5]	1.15	-	9.0	V
$V_{hys(RX)dif}$	differential receiver hysteresis voltage	-12 V $\leq V_{CANL} \leq +12$ V; -12 V $\leq V_{CANH} \leq +12$ V; Normal mode	50	-	300	mV
$I_{O(sc)dom}$	dominant short-circuit output current	$V_{TXD} = 0$ V; $t < t_{to(dom)TXD}$; $V_{CC} = 5$ V				
		pin C_{ANH}; $V_{CANH} = -15$ V to $+40$ V	-100	-70	-	mA
		pin C_{ANL}; $V_{CANL} = -15$ V to $+40$ V	-	70	100	mA
$I_{O(sc)rec}$	recessive short-circuit output current	Normal mode; $V_{TXD} = V_{IO}$ [4]; $V_{CANH} = V_{CANL} = -27$ V to $+32$ V	-5	-	+5	mA
I_L	leakage current	$V_{CC} = V_{IO} = 0$ V or $V_{CC} = V_{IO} =$ shorted to GND via 47 kΩ; $V_{CANH} = V_{CANL} = 5$ V	-5	-	+5	µA
R_i	input resistance	-2 V $\leq V_{CANL} \leq +7$ V; [5] -2 V $\leq V_{CANH} \leq +7$ V	9	15	28	kΩ
ΔR_i	input resistance deviation	0 V $\leq V_{CANL} \leq +5$ V; [5] 0 V $\leq V_{CANH} \leq +5$ V	-3	-	+3	%
$R_{i(dif)}$	differential input resistance	-2 V $\leq V_{CANL} \leq +7$ V; [5] -2 V $\leq V_{CANH} \leq +7$ V	19	30	52	kΩ

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$C_{i(cm)}$	common-mode	[5]	-	-	20	pF
$C_{i(dif)}$	differential input capacitance	[5]	-	-	10	pF
Temperature detection						
$T_{j(sd)}$	shutdown junction temperature	[5]	-	185	-	°C

Note:

(1)　all circuitry is connected to V_{CC} in the other variants.

(2)　All parameters are guaranteed over the virtual junction temperature range by design. Factory testing uses correlated test conditions to cover the specified temperature and power supply voltage range.

(3)　Undervoltage is detected between min and max values. Undervoltage is guaranteed to be detected below min value and guaranteed not to be detected above max value.

(4)　$V_{IO} = V_{CC}$ in non-V_{IO} product variants.

(5)　Not tested in production; guaranteed by design.

(6)　The test circuit used to measure the bus output voltage symmetry and the common-mode voltages (which includes CSPLIT) is shown in Figure 8

10. DYNAMIC CHARACTERISTICS

Table 8. Dynamic characteristics

T_{vj} = -40 °C to +125°C; V_{CC} = 4.5 V to 5.5 V; V_{IO} = 2.91 V to 5.5 V[1]; R_L = 60 Ω; C_L = 100 pF unless specified otherwise; all voltages are defined with respect to ground.[2]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Transceiver timing; pins CANH, CANL, TXD and RXD; see Figure 4, Figure 5 and Figure 7						
$t_{d(TXD\text{-}busdom)}$	delay time from TXD to bus dominant	other variants; Normal mode	-	65	100	ns
$t_{d(TXD\text{-}busrec)}$	delay time from TXD to bus recessive	other variants; Normal mode	-	90	100	ns
$t_{d(busdom\text{-}RXD)}$	delay time from bus dominant to RXD	other variants; Normal mode	-	60	140	ns
$t_{d(busrec\text{-}RXD)}$	delay time from bus recessive to RXD	other variants; Normal mode	-	65	125	ns
$t_{d(TXDL\text{-}RXDL)}$	delay time from TXD LOW to RXD LOW	XLA1044T; Normal mode	50	-	230	ns
		all other variants; Normal mode	50	-	210	ns
$t_{d(TXDH\text{-}RXDH)}$	delay time from TXD HIGH to RXD HIGH	XLA1044T; Normal mode	50	-	230	ns
		all other variants; Normal mode	50	-	210	ns
$t_{bit(bus)}$	transmitted recessive bit width	all variants except XLA1044T				
		tbit(TXD) = 500 ns	435	-	530	ns
		tbit(TXD) = 200 ns	155	-	210	ns
$t_{bit(RXD)}$	bit time on pin RXD	all variants except XLA1044T				
		tbit(TXD) = 500 ns	400	-	550	ns
		tbit(TXD) = 200 ns	120	-	220	ns
Δt_{rec}	receiver timing symmetry	all variants except XLA1044T				
		tbit(TXD) = 500 ns	-65	-	+40	ns
		tbit(TXD) = 200 ns	-45	-	+15	ns
$t_{to(dom)TXD}$	TXD dominant time-out time	VTXD = 0 V; Normal mode	0.8	3	6.5	ms
$t_{d(stb\text{-}norm)}$	standby to normal mode delay time		7	25	47	µs
$t_{wake(busdom)}$	bus dominant wake-up time	Standby mode				
		XLA1044T, GT	0.5	-	3	µs
		all other variants	0.5	-	1.8	µs
$t_{wake(busrec)}$	bus recessive wake-up time	Standby mode				
		XLA1044T, GT	0.5	-	3	µs
		all other variants	0.5	-	1.8	µs
$t_{to(wake)bus}$	bus wake-up time-out tim	Standby mode	0.8	3	6.5	µs
$t_{fltr(wake)bus}$	bus wake-up filter time	Standby mode				
		XLA1044T, GT	0.5	1	3	µs
		all other variants	0.5	-	1.8	µs

Note:

(1)   all circuitry is connected to Vcc in the other variants.

(2)   All parameters are guaranteed over the junction temperature range by design. Factory testing uses correlated test conditions to cover the specified temperature and power supply voltage range.

(3)   See Figure 5.

(4)   Time-out occurs between the min and max values. Time-out is guaranteed not to occur below the min value; time-out is guaranteed to occur above the max value.

(5)   Standby-to-Normal mode transition occurs between the min and max values. It is guaranteed not to occur below the min value; it is guaranteed to occur above the max value.

(6)   A dominant/recessive phase shorter than the min value is guaranteed not be seen as a dominant/recessive bit; a dominant/recessive phase longer than the max value is guaranteed to be seen as a dominant/recessive bit.

(7)   Pulses shorter than the min value are guaranteed to be filtered out; pulses longer than the max value are guaranteed to be processed
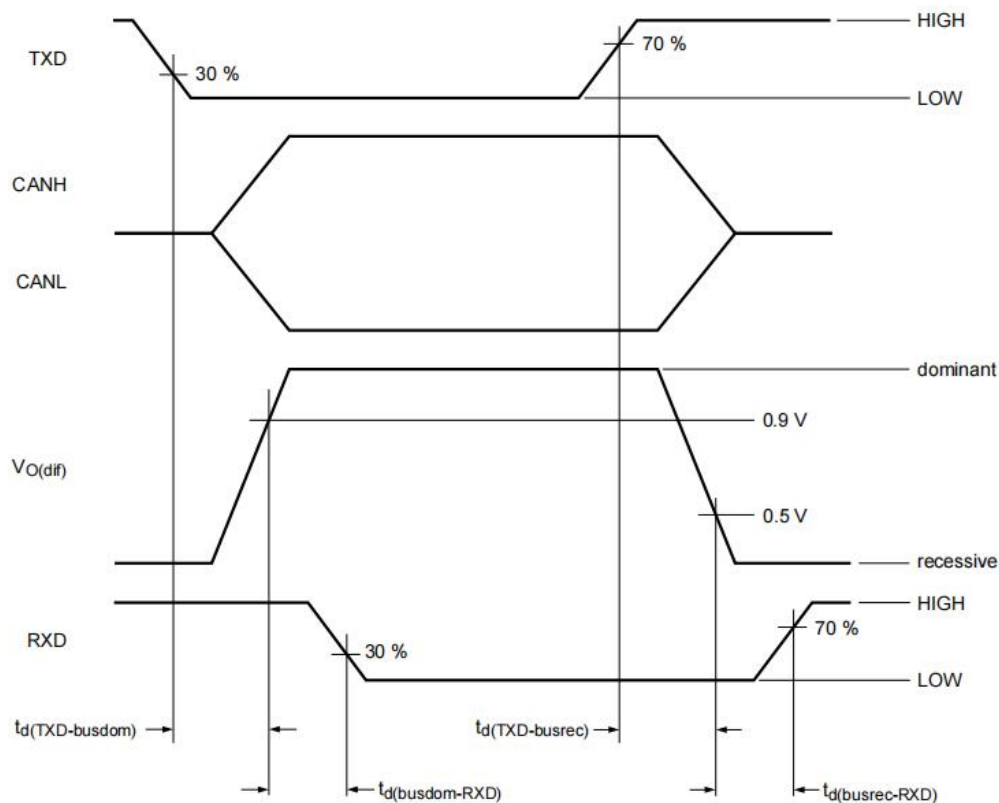
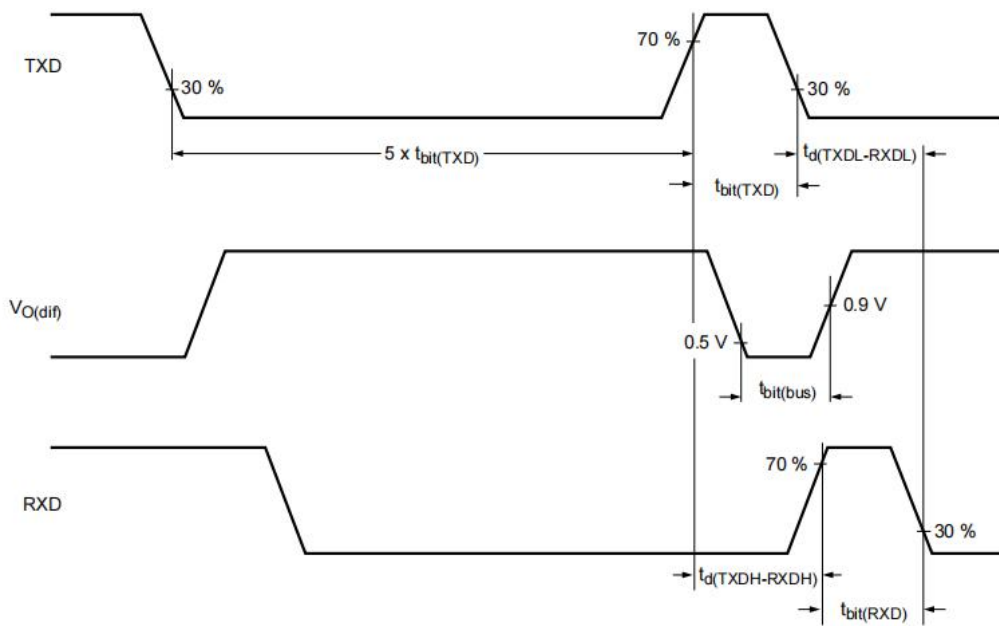**Figure 4. CAN transceiver timing diagram**

Figure 5. CAN FD timing definitions according to ISO 11898-2:2016

11. APPLICATION INFORMATION

11.1. Application diagrams

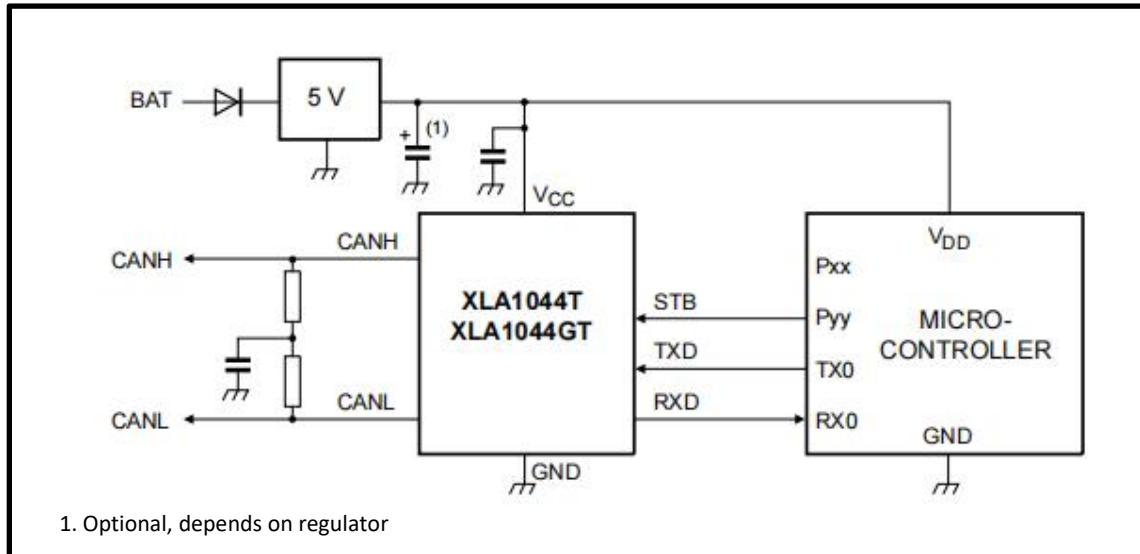1. Optional, depends on regulator

Figure 6. Typical XLA1044 application with a 5 V microcontroller (non-V$_{IO}$ variants)
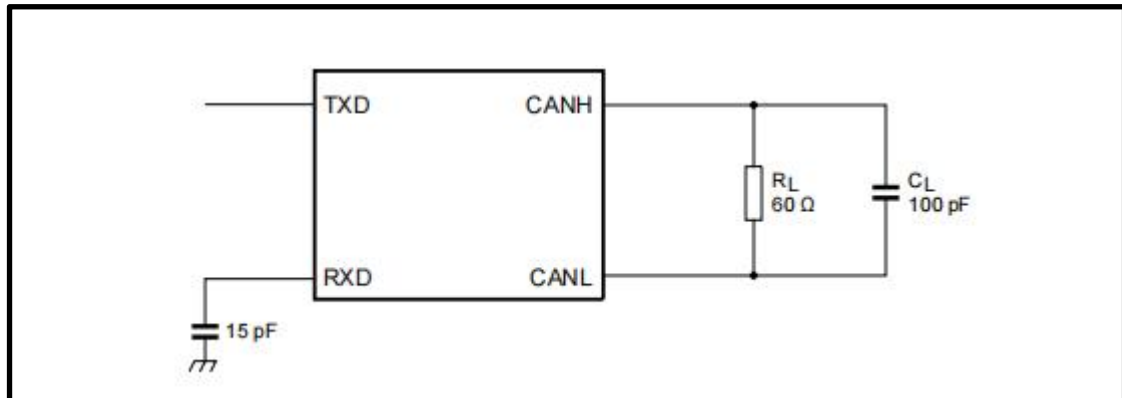
12. TEST INFORMATION

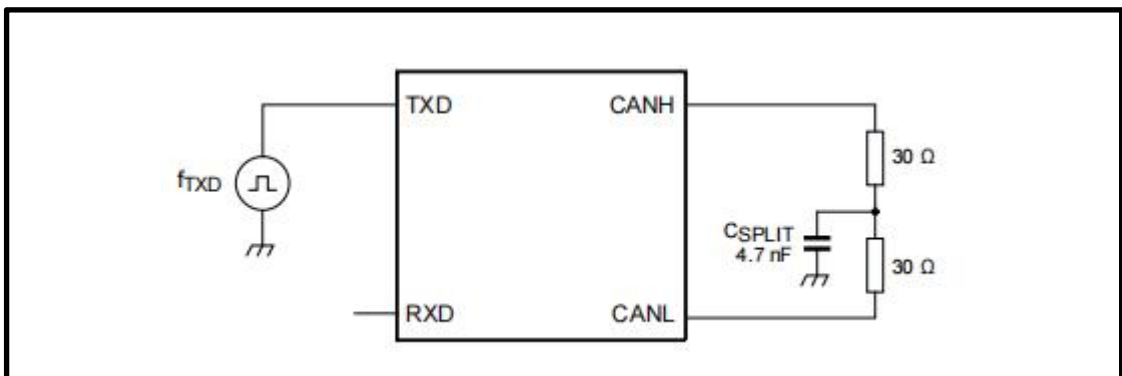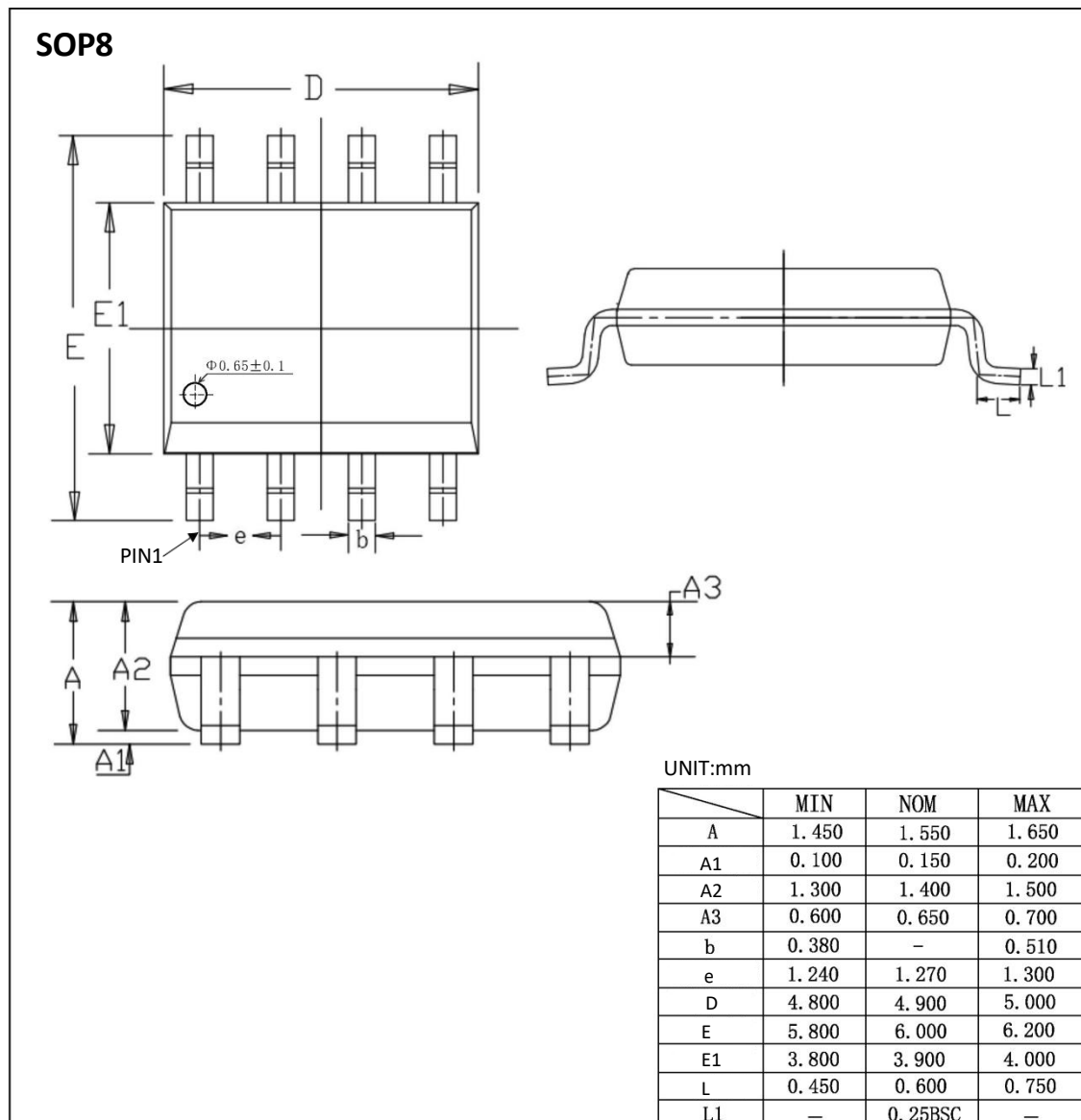**Figure 7. CAN transceiver timing test circuit**

Figure 8. Test circuit for measuring transceiver transmitter driver symmetry

13. ORDERING INFORMATION

Ordering Information

Part Number	Device Making	Package type	Body size (mm)	Temperate (°C)	MSL	Transpo Rt	Package Quantit
XLA1044T/1	XL1044T1	SOP-8	4.90*3.90	-40 to +125	MSL3	T&R	2500
XLA1044GT	XL1044GT	SOP-8	4.90*3.90	-40 to +125	MSL3	T&R	2500

14. DIMENSIONAL DRAWINGS

SOP8

Φ0.65±0.1

PIN1

UNIT:mm

	MIN	NOM	MAX
A	1.450	1.550	1.650
A1	0.100	0.150	0.200
A2	1.300	1.400	1.500
A3	0.600	0.650	0.700
b	0.380	–	0.510
e	1.240	1.270	1.300
D	4.800	4.900	5.000
E	5.800	6.000	6.200
E1	3.800	3.900	4.000
L	0.450	0.600	0.750
L1	—	0.25BSC	—

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